

# Specifications

## ■ Absolute Maximum Ratings (Ta = 25°C)

Item				G3VM-XN(F)	G3VM-4N(F)	Conditions	
Input	LED forward current		I <sub>F</sub>	30 mA		---	
	Repetitive peak LED forward current		I <sub>FP</sub>	1 A		100-μs pulses, 100 pps	
	LED reverse voltage		V <sub>R</sub>	5 V		---	
Output	Output dielectric strength (load voltage)		V <sub>BO</sub>	−60 to 60 V	−400 to 400 V	DC or AC peak value	
				0 to 60 V	0 to 400 V	DC	
	Continuous load current (see note 1)	A connection	I <sub>O</sub>	300 mA	150 mA	---	
				B connection	450 mA		200 mA
				C connection	600 mA		300 mA
	Dielectric strength between I/O terminals (see note 2)			V <sub>I-O</sub>	2,500 V AC		1 min
Ambient temperature			T <sub>a</sub>	−20 to 85°C		With no icing or condensation	
Storage temperature			T <sub>stg</sub>	−55 to 100°C		With no icing or condensation	
Max. soldering temperature and time			---	260°C		10 s	

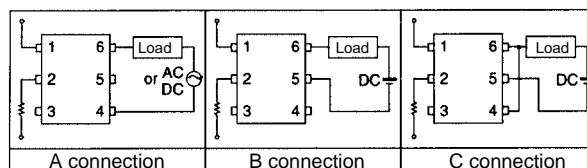
Note: 1. The load current attenuation rates for the different types of connection are as follows:

G3VM-XN(F): A: −3.0 mA/°C; B: −4.5 mA/°C; C: −6.0 mA/°C

G3VM-4N(F): A: −1.5 mA/°C; B: −2.0 mA/°C; C: −3.0 mA/°C

2. The dielectric strength between I/O terminals was measured with voltage applied to all of the LED pins and with voltage applied to all of the light-receiving parts respectively.

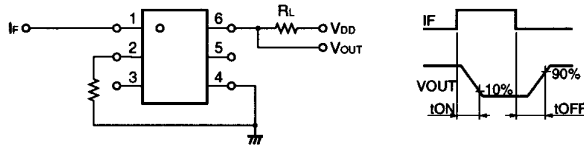
## Connection Circuit Diagram



## ■ Electrical Performance (Ta = 25°C)

Item			G3VM-XN(F)	G3VM-4N(F)	Unit	Conditions
Input	LED forward current	$V_F$	1.2 V min, 1.7 V max.		V	$I_F = 10 \text{ mA}$
	Trigger LED forward current	$I_{FT}$	5 mA max.			$I_O = 300 \text{ mA}$ (G3VM-XN(F)) $I_O = 150 \text{ mA}$ (G3VM-4N(F))
Output	Output ON resistance	A connection	$R_{ON}$	2 Ω max.	12 Ω max.	$I_F = 10 \text{ mA}$ $I_O = \text{MAX}$
		B connection		1 Ω max.	6 Ω max.	
		C connection		0.5 Ω max.	3 Ω max.	
	Switching current leakage	$I_{LEAK}$	1.0 μA max.		μA	$V_{off} = 60 \text{ V}$ (G3VM-XN(F)) $V_{off} = 400 \text{ V}$ (G3VM-4N(F))
Operate time		$T_{ON}$	0.5 ms max.	1.0 ms max.	ms	$R_L = 200 \text{ Ω}$ (see note)
Release time		$T_{OFF}$	0.5 ms max.	1.0 ms max.	ms	$V_{DD} = 20 \text{ V}$ , $I_F = 10 \text{ mA}$
Floating capacity between I/O terminals		$C_{I-O}$	0.8 pF, TYP		pF	f = 1 MHz

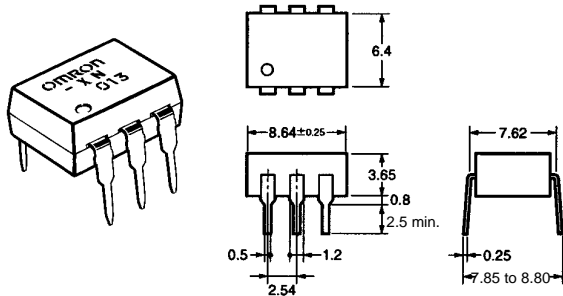
**Note:** The operate and release time were measured in the way shown below.



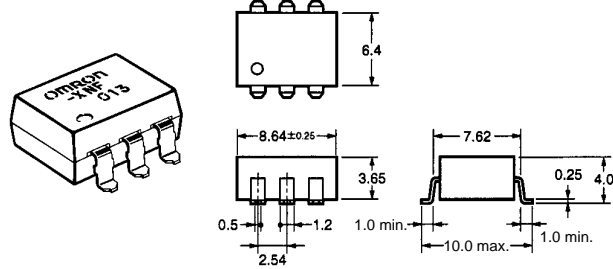
## Dimensions

**Note:** All units are in millimeters unless otherwise indicated.

**G3VM-XN  
G3VM-4N**



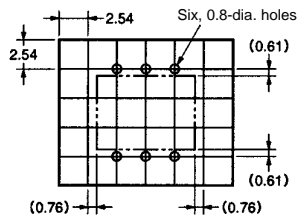
**G3VM-XNF  
G3VM-4NF**



**Note:** "G3VM" is not printed on the actual product.

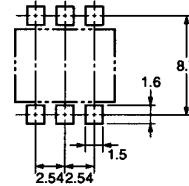
### ■ PCB Dimensions (Bottom View)

**G3VM-XN  
G3VM-4N**



### ■ Actual Mounting Pad Dimensions (Recommended Value, Top View)

**G3VM-XNF  
G3VM-4NF**

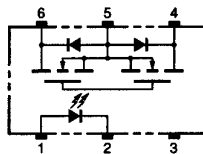


**Note:** Mounting pad dimensions shown are a top view.

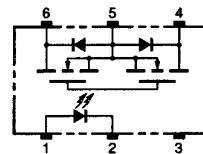
## Installation

### ■ Terminal Arrangement/Internal Connection (Top View)

**G3VM-XN  
G3VM-4N**



**G3VM-XNF  
G3VM-4NF**



## Precautions

**⚠ WARNING**

Be sure to turn OFF the power when wiring the Relay, otherwise an electric shock may be received.

**⚠ WARNING**

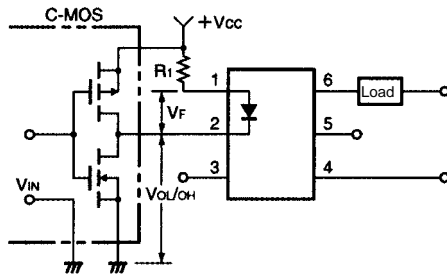
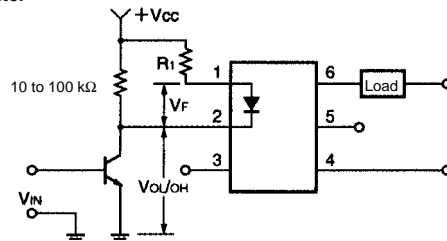
Do not touch the charged terminals of the SSR, otherwise an electric shock may be received.

**⚠ Caution**

Do not apply overvoltage or overcurrent to the I/O circuits of the SSR, otherwise the SSR may malfunction or burn.

**⚠ Caution**

Be sure to wire and solder the Relay under the proper soldering conditions, otherwise the Relay in operation may generate excessive heat and the Relay may burn.

**Typical Relay Driving Circuit Examples****C-MOS****Transistor**

Use the following formula to obtain the LED current limiting resistance value to assure that the relay operates accurately.

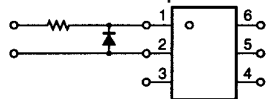
$$R_1 = \frac{V_{CC} - V_{OL} - V_F \text{ (ON)}}{5 \text{ to } 20 \text{ mA}}$$

Use the following formula to obtain the LED forward voltage value to assure that the relay releases accurately.

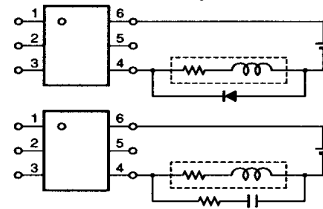
$$V_F \text{ (OFF)} = V_{CC} - V_{OH} < 0.8 \text{ V}$$

**Protection from Surge Voltage on the Input Terminals**

If any reversed surge voltage is imposed on the input terminals, insert a diode in parallel to the input terminals as shown in the following circuit diagram and do not impose a reversed voltage value of 3 V or more.

**Surge Voltage Protection Circuit Example****Protection from Spike Voltage on the Output Terminals**

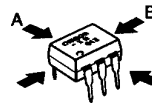
If a spike voltage exceeding the absolute maximum rated value is generated between the output terminals, insert a C-R snubber or clamping diode in parallel to the load as shown in the following circuit diagram to limit the spike voltage.

**Spike Voltage Protection Circuit Example****Unused Terminals (6-pin only)**

Terminal 3 is connected to the internal circuit. Do not connect anything to terminal 3 externally.

**Pin Strength for Automatic Mounting**

In order to maintain the characteristics of the relay, the force imposed on any pin of the relay for automatic mounting must not exceed the following.

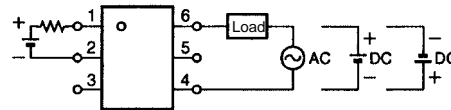
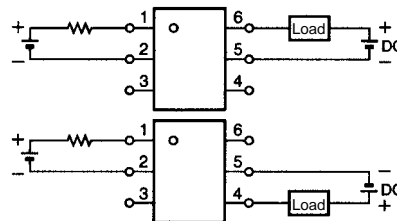
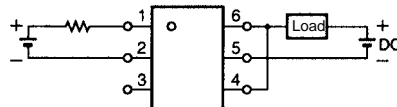


In direction A: 1.96 N

In direction B: 1.96 N

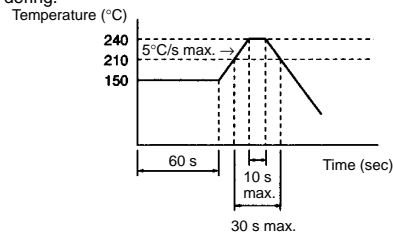
**Load Connection**

Do not short-circuit the input and output terminals while the relay is operating or the relay may malfunction.

**AC Connection****DC Single Connection****DC Parallel Connection****Solder Mounting**

Maintain the following conditions during manual or reflow soldering of the relays in order to prevent the temperature of the relays from rising.

1. Pin Soldering
  - Solder each pin at a maximum temperature of 260°C within 10 s.
2. Reflow Soldering
  - a. Solder each pin at a maximum temperature of 260°C within 10 s.
  - b. Make sure that the ambient temperature on the surface of the resin casing is 240°C max. for 10 s maximum.
  - c. The following temperature changes are recommendable for soldering.



**ALL DIMENSIONS SHOWN ARE IN MILLIMETERS.**

To convert millimeters into inches, multiply by 0.03937. To convert grams into ounces, multiply by 0.03527.

Cat. No. K112-E1-1    **In the interest of product improvement, specifications are subject to change without notice.**

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